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- AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Application No. 09/664,094
Attorney Docket No. Q60884

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line; and

a ground plate; and

another signal line disposed close to the signal line and on an opposite side of said ground plate;

wherein at least one through hole is formed in said signal line, and an inner wall of said through hole is only directly electrically connected to said signal line.

2. (Currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line; and

a ground plate; and

another signal line disposed close to the signal line and on an opposite side of said ground plate;

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole is only directly electrically connected to said ground plate.

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3. (Currently amended): A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 2,

wherein ~~the-a~~ size of said at least one hole formed in said ground plate is determined such that ~~the-an~~ AC coupling between the signal line and ~~the~~ another signal line disposed close to the signal line and on the opposite side of said ground plate is decreased and ~~the-a~~ characteristic impedance of said signal transmission line is increased.

4. (Currently amended): A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 2,

wherein ~~the-a~~ number of said at least one through hole formed in said ground plate is determined such that ~~the-an~~ AC coupling between the signal line and ~~the~~ another signal line disposed close to the signal line and on the opposite side of said ground plate is decreased and ~~the-a~~ characteristic impedance of said signal transmission line is increased.

5. (Currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:

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a signal line; and

a ground plate; and ;

another signal line disposed close to the signal line and on an opposite side of said ground plate;

wherein at least one through hole is formed in said signal line, and an inner wall of said through hole which is formed in said signal line is only directly electrically connected to said signal line, and

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole which is formed in said ground plate is only directly electrically connected to said ground plate.

6. (Currently amended): A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 5,

wherein the-a size of said at least one through hole formed in said ground plate among the signal line and the ground plate is determined such that the-an AC coupling between the signal line and the another signal line disposed close to the signal line and on the opposite side of said ground plate is decreased and the-a characteristic impedance of said signal transmission line is increased.

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7. (Currently amended): A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 5,

wherein ~~the-a~~ number of said at least one through hole formed in said ground plate among holes formed in both of the signal line and the ground plate is determined such that ~~the-an~~ AC coupling between the signal line and the another signal line disposed close to the signal line on the opposite side of said ground plate is decreased and ~~the-a~~ characteristic impedance of said signal transmission line is increased.

8. (Currently amended): A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 2,

wherein said at least one through hole in said ground plate is formed at a position where the another ~~other~~ signal line is not disposed or said at least one hole in said ground plate is made small so as to reduce ~~the-an~~ AC coupling with the ~~one~~ signal line when formed at a position where the another ~~other~~ signal line is disposed.

9. (Currently amended): A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 1, wherein, instead of at least one hole formed in said signal line or in said ground plate,

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a plurality of slit holes are formed by forming said signal line or said ground plate of a plurality of thin strips and by connecting the these thin strips at respective those terminal ends of the thin strips.

10. (New): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed close to the signal line and on an opposite side of the ground plate;

wherein at least one through hole is formed in said signal line and an inner wall of said through hole is directly electrically connected to said signal line, and said at least one through hole comprises a plurality of through holes formed along a longitudinal direction of a signal transmission line and arranged at equal spaces or in a same pattern.

11. (New): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed close to the signal line and on an opposite side of the ground plate;

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wherein at least one through hole is formed in said signal line and an inner wall of said through hole is directly electrically connected to said signal line, and said at least one through hole comprises a plurality of through holes formed along a longitudinal direction of a signal transmission line and arranged at equal spaces or in a same pattern.

12. (New): A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 11, wherein a size of said at least one through hole comprising a plurality of through holes formed in said ground plate is determined such that an AC coupling between the signal line and the another signal line disposed close to the signal line and on the opposite side of said ground plate is decreased and a characteristic impedance of said signal transmission line is increased.